

Title (en)  
SEMICONDUCTOR CHIP AND PRODUCTION METHOD FOR A HOUSING

Title (de)  
HALBLEITERCHIP UND HERSTELLUNGSVERFAHREN FÜR EIN GEHÄUSE

Title (fr)  
PUCE A SEMI-CONDUCTEUR ET PROCEDE DE PRODUCTION POUR UN BOITIER

Publication  
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Application  
**EP 02714075 A 20020227**

Priority

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Abstract (en)  
[origin: WO02069386A1] The invention relates to a selective covering, which covers the terminal contact surfaces (3, 4) and bonding wires (5) with a casting compound (8) and which leaves active areas exposed, particularly a contact area (6) for a finger in a fingerprint sensor. To this end, the chip surface is selectively adapted by the provision of a varying roughness or coating and/or the viscosity of the casting compound is modified by irradiating the same.

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Citation (search report)  
See references of WO 02069386A1

Citation (examination)

- JP H1074869 A 19980317 - MOTOROLA INC
- EP 1041628 A2 20001004 - IMEC INTER UNI MICRO ELECTR [BE]

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